APPARATUS AND METHOD FOR ENHANCING WET STRIPPING OF PHOTORESIST

ABSTRACT OF THE INVENTION

An apparatus and method for enhancing uniformity in the spread of a process chemical such as a liquid strip chemical or solvent over the surface of a wafer to enhance contact of all areas of the wafer with the chemical, such as during the removal or stripping of photoresist from the wafer. The apparatus includes a wafer chuck having a heater for heating the wafer chuck and a wafer supported on the chuck. The wafer chuck and wafer are initially heated to a desired target temperature which is substantially the same as the temperature of the process chemical, after which the process chemical is dispensed onto the surface of the rotating wafer. The process chemical is maintained at the desired target temperature on the heated wafer to maintain a low viscosity of the process chemical and thus, enhance uniformity in distribution or spread of the process chemical from the center to the peripheral regions on the wafer surface.

FIG. 3